

SJSemi Company Profile

2020年3月

P I L L A R S O F P E R F O R M A N C E





中芯长电半导体

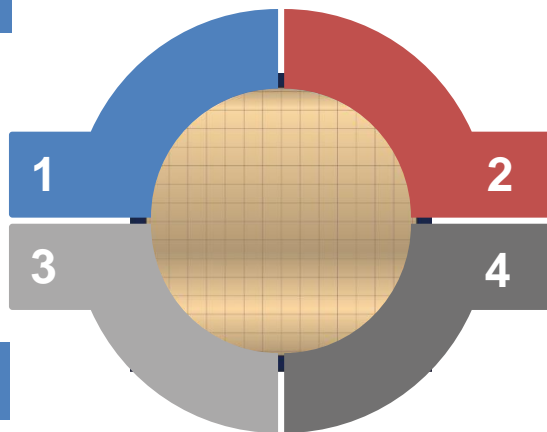
中国第一家12英寸中段硅片高密度凸块加工企业
China's first Middle-End-Of-Line Entity that focuses
on advanced bumping production

全新的公司：

为您提供多种职业选择！

新兴的行业：

为您提供无限的职业发展前途！



纯外资企业和国际化的团队：

为您提供一个学习国际领先技术及管理模式的平台！

美丽的城市：

苏锡常生活圈，舒适和低成本
的居住环境，便利的交通

Mission

SJSemi is born for China's First Dedicated 12" Bumping Line to support industry advancement while proceeding for 3DIC.

Strategy

Comparative competitive advantage by leveraging Front-end manufacturing and quality system as a pure play Middle-end Foundry.



Founded: 2014 Sep.
Capital: **USD330M**

Process Portfolio

- 12"CuP, LF bump, WLP, DPS, CP
- 8" CuP, LF Bump, WLP, DPS, CP
- 2.5D/3DIC Wafer Level SiP Packaging

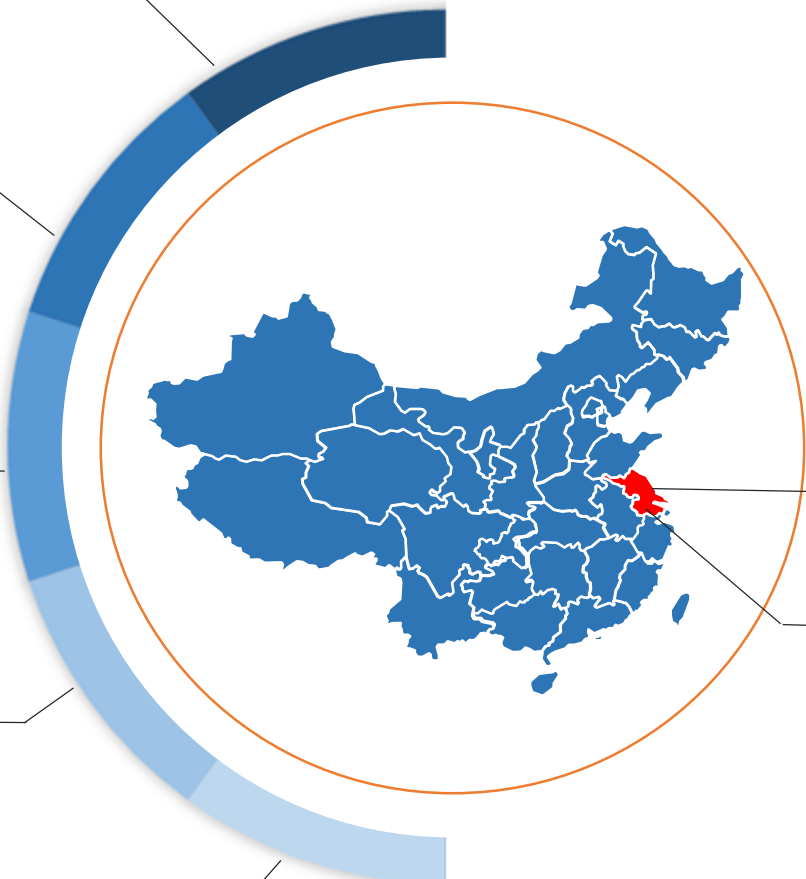
Capacity

- CP: 200+ testers
- 12" Bumping : 40K/M
- 8" Bumping : 25K/M
- DPS : 180KK/M

Employee

- Jiangyin Site: **700+**
- Shanghai Site: **500+**

Shareholders
SMIC, China IC fund
JCET, Qualcomm



Shanghai

Jiangyin



Project Announcement



2nd round \$280M



5B RMB from CDB



Merge M1



Taking off



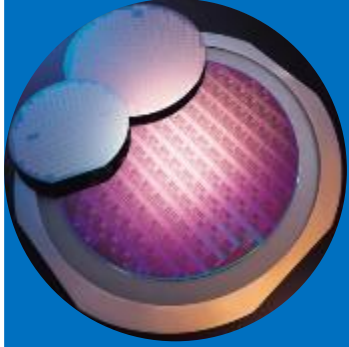
Phase I Production N28 / N14nm HVM



Phase I Production J2A Construction Complete



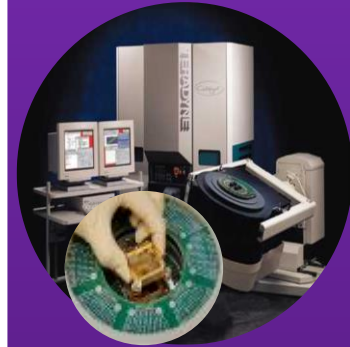
ASIC



- Logic, Mixed Signal/RF CMOS, High Voltage, SoC, DRAM, Flash, EEPROM, CIS and LCoS Micro-D

SMIC & Other Foundries


8"/12" Bumping/WLP



- Mask Design
- Solder Bump
- Cu Pillar
- RDL Ball Drop
- Reliability Test

SJ-SH 200mm
SJ-JY 300mm


Probe Testing



- Logic & Memory Testers
- Vast Coverage on Device Types
- Low/High Temperature Option Available

SJ-SH & JY


Die Process



- Backside grinding
- Backside Lamination
- Laser Marking
- Wafer Dicing
- Tape and Reel

SJ-SH & JY

Drop Ship



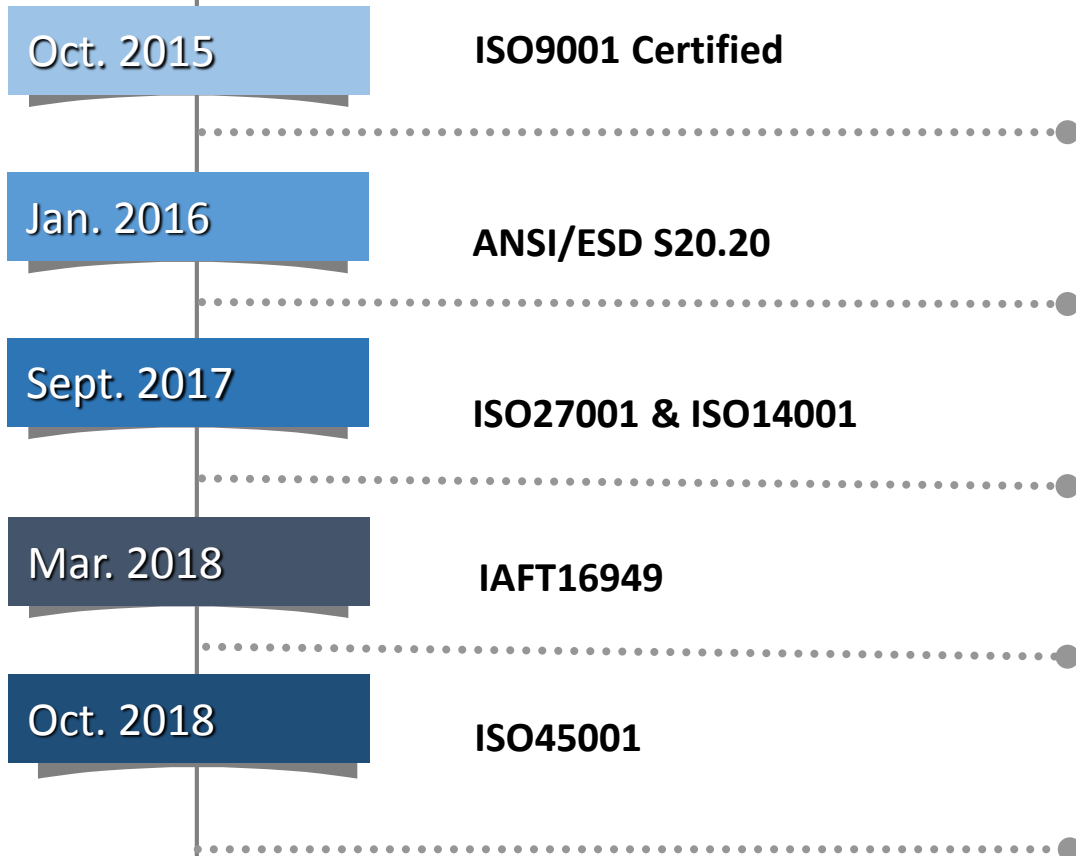
- Direct shipment to end customers and designated location

SJ-SH & JY

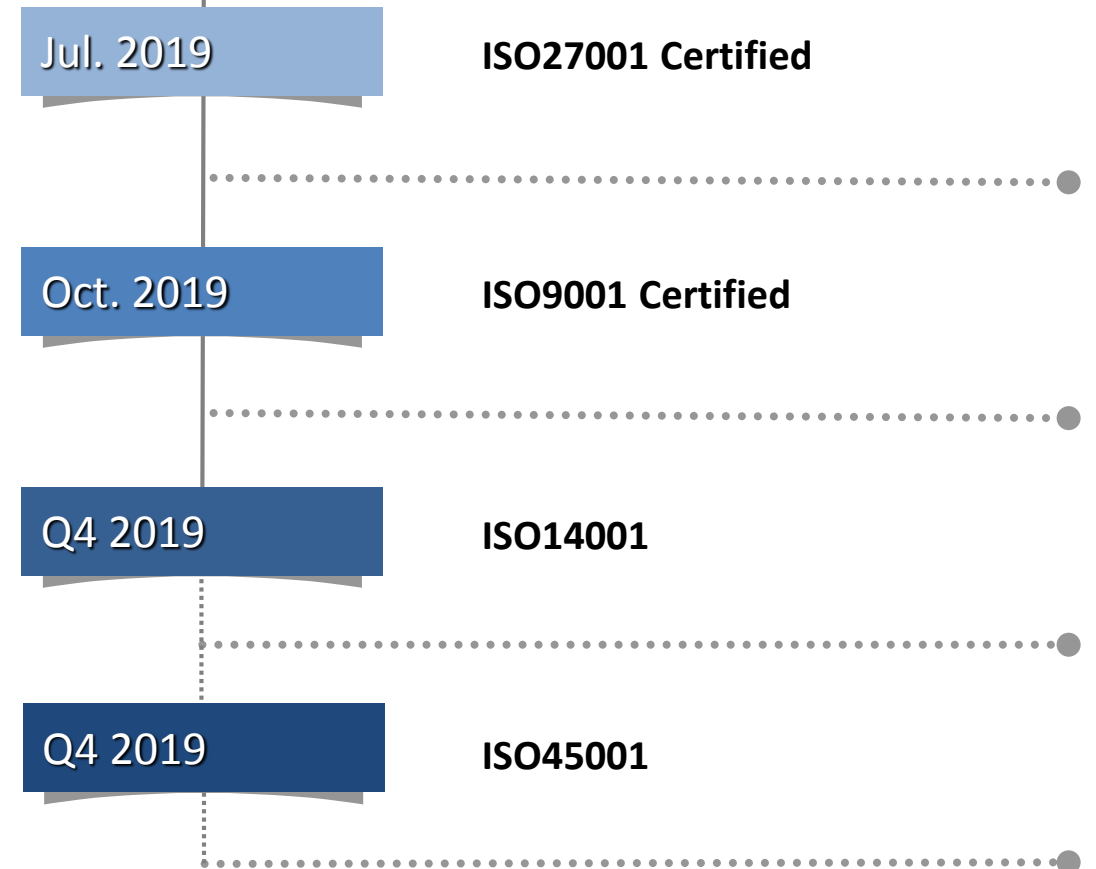


One Stop Service

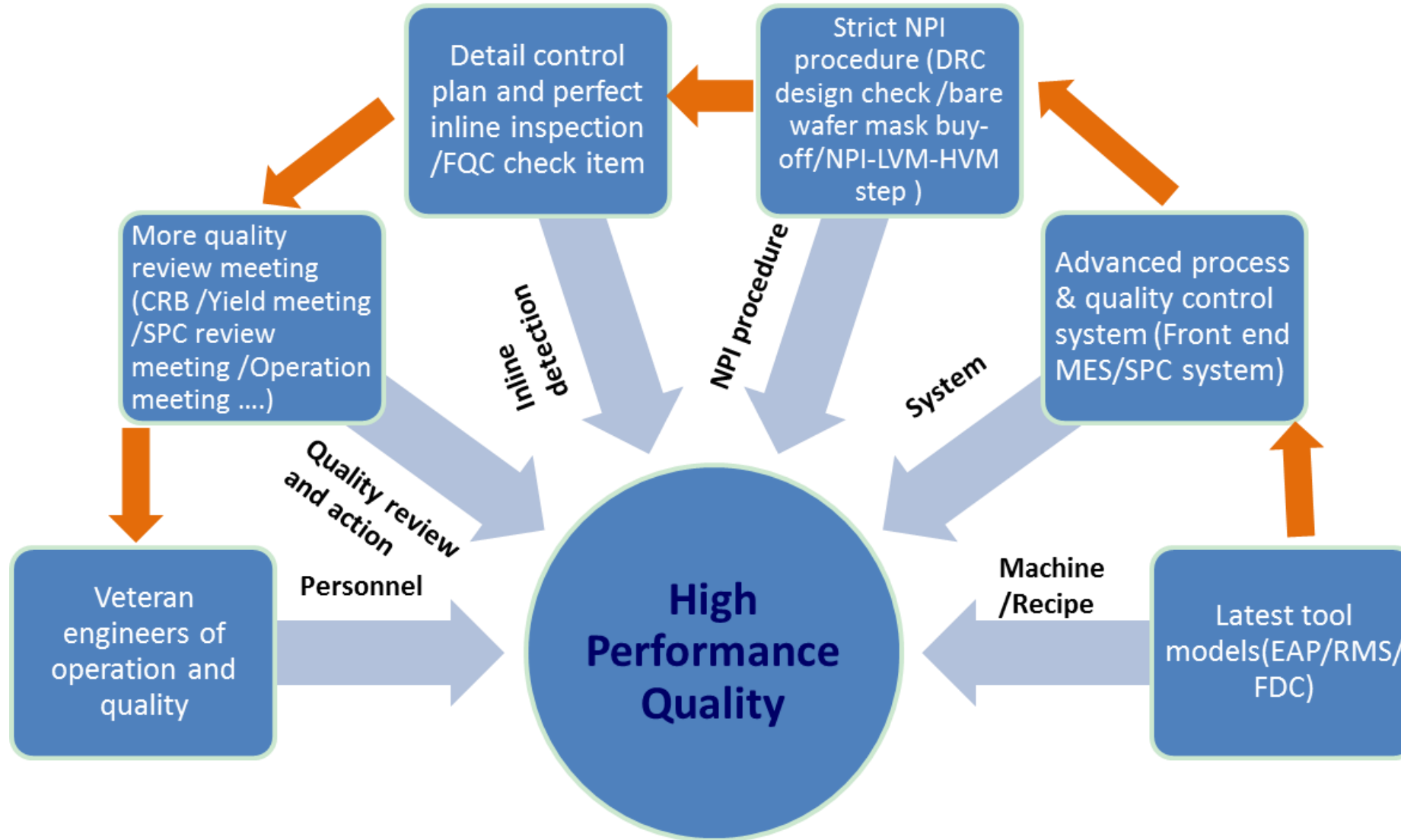
12 inch Line



8 inch Line



Six Key Points to Keep High Performance Quality



World's First 5G mm-Wave Ultra-Wideband Dual Polarization Antenna Using Stackable Packaging – SmartPoser™

Cheng Chung Lin
Senior Director , R&D
SJ Semiconductor(JiangYin) Corp.





- ◆ \$1.2B investment toward 300K/M capacity, focusing on Bumping, Sorting, RDL, TSV, Smart Interposer and 2.5D/3DIC

- ◆ J1 Capacity: 40K WPM
- ◆ J2A ready for production 2020B







1、技术员：

学历要求：大专；

专业要求：机电一体化、机械、电子、自动化、微电子、测量控制、计算机、电子电路等相关专业；

岗位职责：机台安装调试、工艺参数维护、日常维护保养、异常处理；确保产线正常运行；

综合收入：4000-6000/月，奖金另计；

2、一线作业人员：

学历要求：高中-中专；

专业要求：不限；

岗位职责：机台操作、异常维护，确保订单及时完成；

综合收入：4000-5000/月，奖金另计；

薪资结构

职位工资

半年度绩效奖金

基于市场薪资增长
及员工绩效的年度
调薪政策

法律/条例规定福利

五险一金

法定年假

公司福利

补充商业保险

交通补贴

福利年假

福利体检

统一安排住宿

免费工作餐

部门团队活动

公司地址：江苏省无锡江阴市东盛西路6号A8-4

联系电话：0510-86976720

简历投递:

- 1、HR邮箱：Carol.Zhang@sjsemi.com（请注明：应聘岗位—姓名—所在院校—专业）
- 2、微信：扫描二维码与HR直接对话



Thanks